

# SOT631-3

plastic low profile fine-pitch ball grid array package; 208 balls; body 15 x 15 x 1.05 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA208
<b>Package type industry code</b>	LFPGA208
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-205
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-10-2003

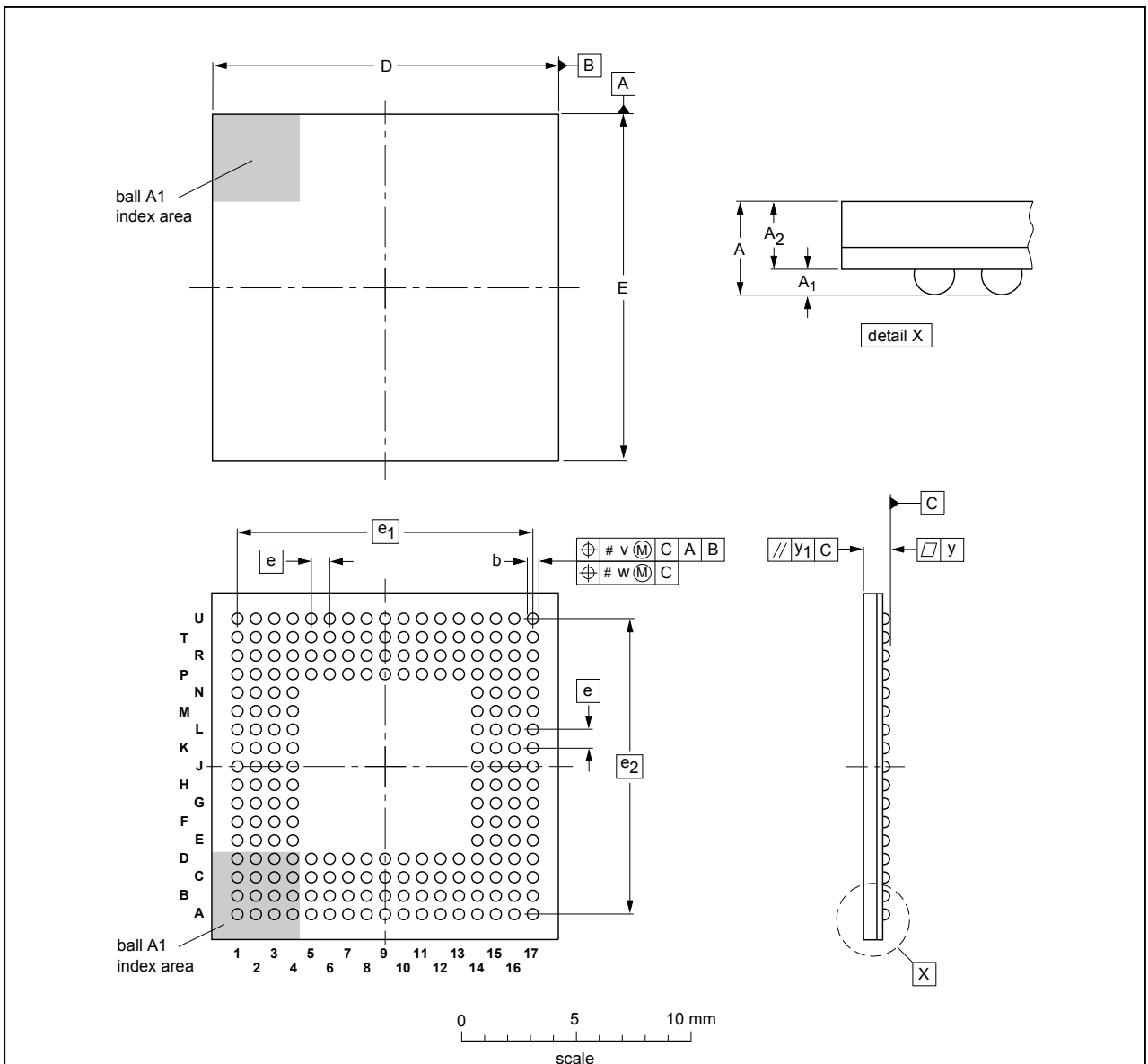
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.9	-	15	15.1	mm
E	package width	14.9	-	15	15.1	mm
A	seated height	[tbd]	-	1.4	1.4	mm
A <sub>2</sub>	package height	0.96	-	1.05	1.14	mm
n <sub>2</sub>	actual quantity of termination	-	-	208	-	



## 2. Package outline

LFBGA208: plastic low profile fine-pitch ball grid array package; 208 balls; body 15 x 15 x 1.05 mm SOT631-3



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1.4	0.37 0.27	1.14 0.96	0.45 0.35	15.1 14.9	15.1 14.9	0.8	12.8	12.8	0.15	0.08	0.12	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT631-3	---	MO-205	---			03-10-20

Fig. 1. Package outline LFBGA208 (SOT631-3)

### 3. Soldering

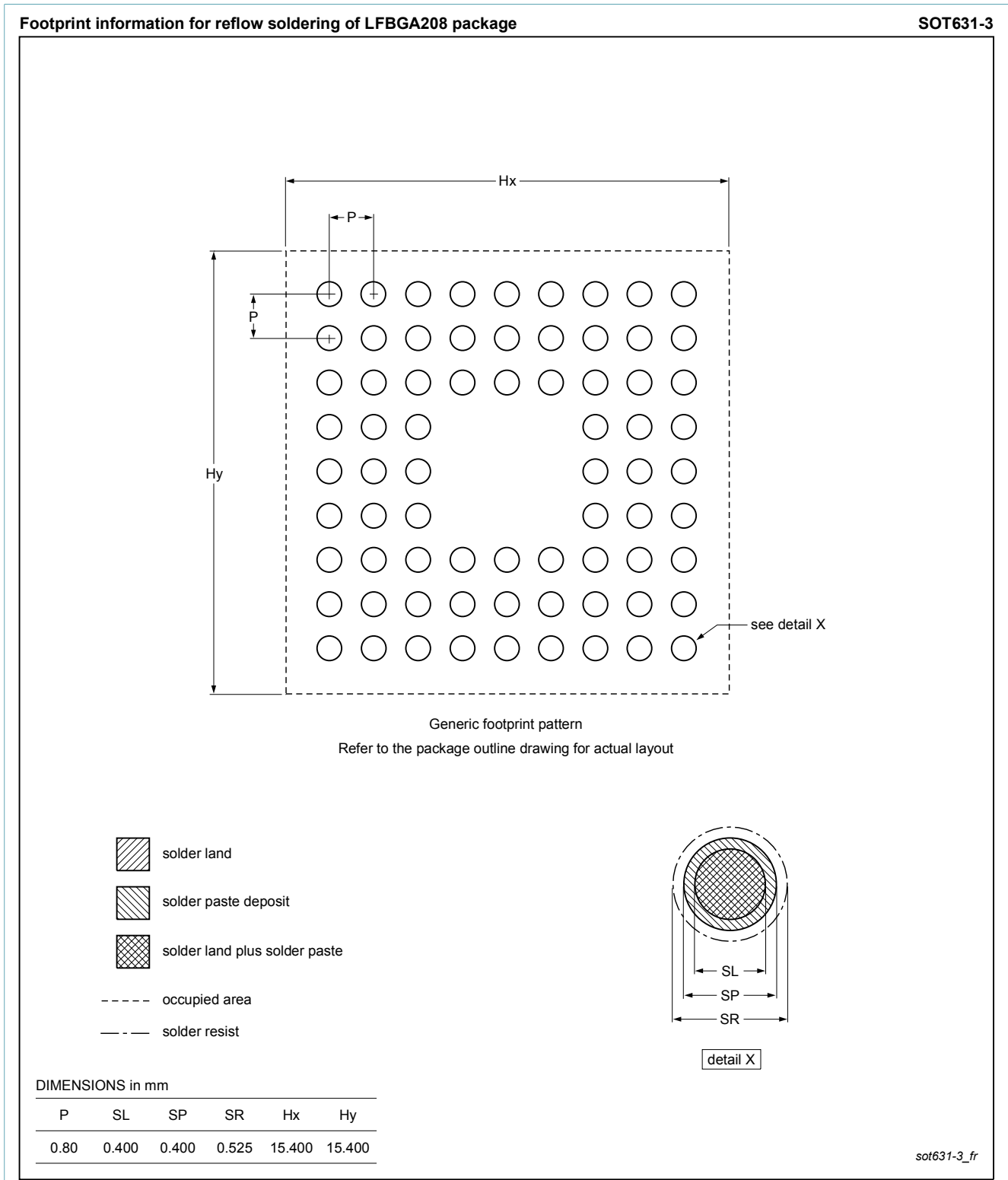


Fig. 2. Reflow soldering footprint for LFBGA208 (SOT631-3)

## 4. Legal information

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